

LNPT[™] THERMOCOMP[™] COMPOUND GF004

GF-1004

REGION AMERICAS

DESCRIPTION

LNP THERMOCOMP GF004 compound is based on Polysulfone (PSU) resin containing 20% glass fiber.

GENERAL INFORMATION	
Features	High stiffness/Strength, High temperature resistance, No PFAS intentionally added
Fillers	Glass Fiber
Polymer Types	Polysulfone (PSU)
Processing Techniques	Injection Molding

INDUSTRY	SUB INDUSTRY
Building and Construction	Building Component
Consumer	Sport/Leisure, Personal Accessory, Home Appliances, Commercial Appliance
Electrical and Electronics	Mobile Phone - Computer - Tablets
Industrial	Electrical, Defense

TYPICAL PROPERTY VALUES

Revision 20231109

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
MECHANICAL ⁽¹⁾			
Tensile Stress, yield	91	MPa	ASTM D638
Tensile Stress, break	91	MPa	ASTM D638
Tensile Strain, yield	2.3	%	ASTM D638
Tensile Strain, break	2.3	%	ASTM D638
Tensile Modulus, 50 mm/min	6200	MPa	ASTM D638
Flexural Stress	137	MPa	ASTM D790
Flexural modulus	6200	MPa	ASTM D790
Flexural Stress	145	MPa	ISO 178
Flexural Modulus	6000	MPa	ISO 178
IMPACT ⁽¹⁾			
Izod Impact, unnotched, 23°C	427	J/m	ASTM D4812
Izod Impact, notched, 23°C	53	J/m	ASTM D256
Instrumented Dart Impact Energy @ peak, 23°C	10	J	ASTM D3763
Izod Impact, unnotched 80*10*4 +23°C	31	kJ/m ²	ISO 180/1U
Izod Impact, notched 80*10*4 +23°C	6	kJ/m ²	ISO 180/1A
THERMAL ⁽¹⁾			
HDT, 0.45 MPa, 3.2 mm, unannealed	178	°C	ASTM D648
HDT, 1.82 MPa, 3.2mm, unannealed	173	°C	ASTM D648
CTE, -40°C to 40°C, flow	2.52E-05	1/°C	ASTM E831
CTE, -40°C to 40°C, xflow	5.22E-05	1/°C	ASTM E831

PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
CTE, -40°C to 40°C, flow	2.50E-05	1/°C	ISO 11359-2
CTE, -40°C to 40°C, xflow	5.20E-05	1/°C	ISO 11359-2
HDT/Bf, 0.45 MPa Flatw 80*10*4 sp=64mm	180	°C	ISO 75/Bf
HDT/Af, 1.8 MPa Flatw 80*10*4 sp=64mm	174	°C	ISO 75/Af
PHYSICAL ⁽¹⁾			
Density	1.41	g/cm ³	ASTM D792
Moisture Absorption, (23°C/50% RH/24 hrs)	0.1	%	ASTM D570
Mold Shrinkage, flow, 24 hrs ⁽²⁾	0.6	%	ASTM D955
Mold Shrinkage, xflow, 24 hrs ⁽²⁾	0.9	%	ASTM D955
Mold Shrinkage, flow, 24 hrs ⁽²⁾	0.64	%	ISO 294
Mold Shrinkage, xflow, 24 hrs ⁽²⁾	0.85	%	ISO 294
Density	1.4	g/cm ³	ISO 1183
INJECTION MOLDING ⁽³⁾			
Drying Temperature	120 – 150	°C	
Drying Time	4	Hrs	
Maximum Moisture Content	0.05	%	
Melt Temperature	360 – 370	°C	
Front - Zone 3 Temperature	350 – 360	°C	
Middle - Zone 2 Temperature	340 – 350	°C	
Rear - Zone 1 Temperature	325 – 340	°C	
Mold Temperature	150	°C	
Back Pressure	0.2 – 0.3	MPa	
Screw Speed	30 – 60	rpm	

- (1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.
- (2) Measurements made from laboratory test coupon. Actual shrinkage may vary outside of range due to differences in processing conditions, equipment, part geometry and tool design. It is recommended that mold shrinkage studies be performed with surrogate or legacy tooling prior to cutting tools for new molded article.
- (3) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

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